

**SMT470-23**

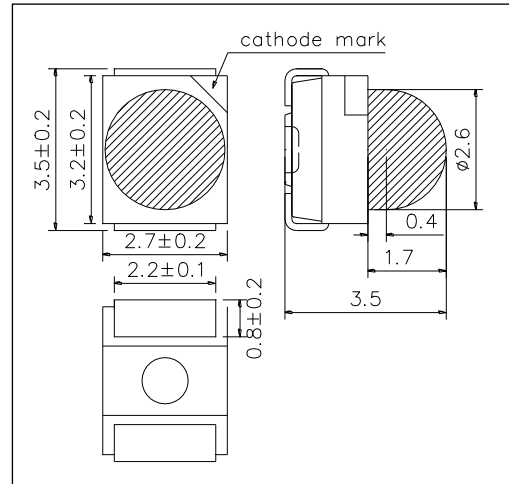
High Performance Blue Color TOP LED with Lens

SMT470-23 consists of an InGaN LEDs mounted on the lead frame as TOP LED package with plastic ball lens and is 18mW typical of output power and 2800mcd of brightness. It emits a spectral band of radiation at 465nm.

<Specifications>

1. Product Name: TOP LED
2. Type Number: SMT470-23
3. Chip:
  - Chip Material: InGaN
  - Peak Wavelength: 465nm
4. Package
  - Lead Frame Die: Silver Plated
  - Package Resin: PPA Resin
  - Lens: Epoxy Resin
  - Diameter:  $\Phi 2.6$ mm

Outer Dimension (Unit:mm)



Absolute Maximum Ratings				
Item	Symbol	Maximum Rated Value	Unit	Ambient Temperature
Power Dissipation	PD	180	mW	Ta=25°C
Forward Current	IF	50	mA	Ta=25°C
Reverse Voltage	VR	5	V	Ta=25°C
Thermal Resistance	Rthja	200	K/W	
Junction Temperature	Tj	100	°C	
Operating Temperature	TOPR	-20 ~ +80	°C	
Storage Temperature	TSTG	-30 ~ +80	°C	
Soldering Temperature*	TSOL	255	°C	

\* Soldering condition must be completed within 10 second at 255°C.

Electro-Optical Characteristics [Ta=25°C typ.]						
Item	Symbol	Condition	Minimum	Typical	Maximum	Unit
Forward Voltage	VF	IF=20mA		3.3	4.0	V
Reverse Current	IR	VR=5V			10	uA
Total Radiated Power*	PO	IF=20mA		18.0		mW
Radiant Intensity	IE	IF=20mA		30		mW/sr
Brightness**	IV	IF=20mA		2800		mcd
Peak Wavelength	$\lambda P$	IF=20mA	465	465	475	nm
Half Width	$\Delta\lambda$	IF=20mA		25		nm
Viewing Half Angle	$\theta 1/2$	IF=20mA		$\pm 15$		deg

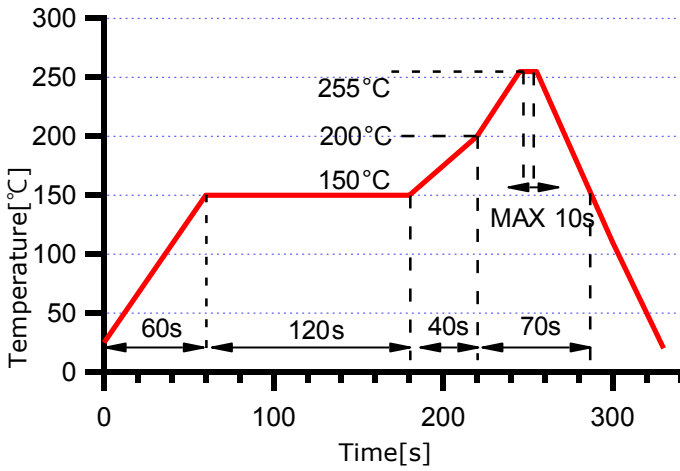
\* Measured by Photodyne #500

\*\* Measured by Tektronix J-16

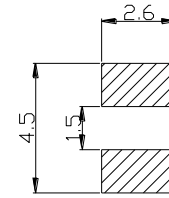


**SMD Application**

IR-Reflow Soldering Profile for lead free soldering



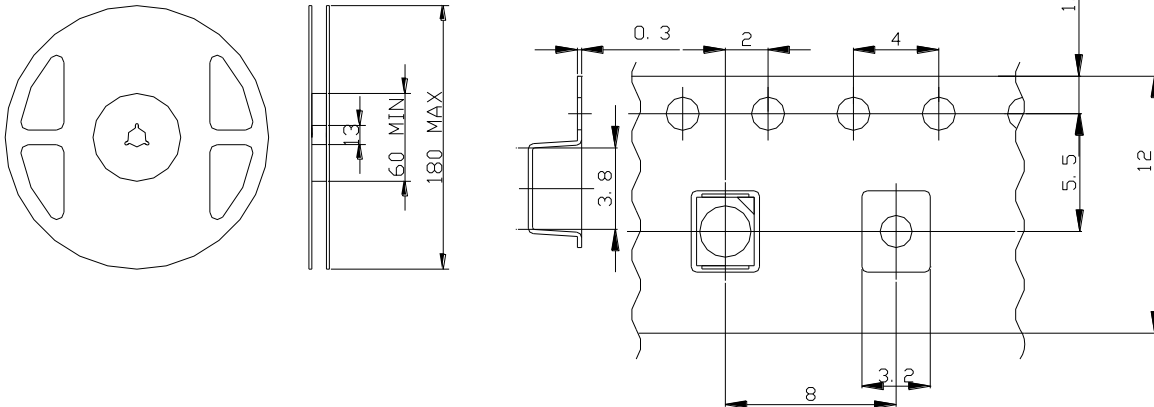
Recommended Land Layout (Unit:mm)



Don't put stress on SMD and a circuit board after soldering

**SMD Packing**

Tape and Reel Dimensions (Unit:mm)



**Wrapping**

Moisture barrier bag aluminum laminated film with a desiccant to keep out the moisture absorption during the transportation and storage.